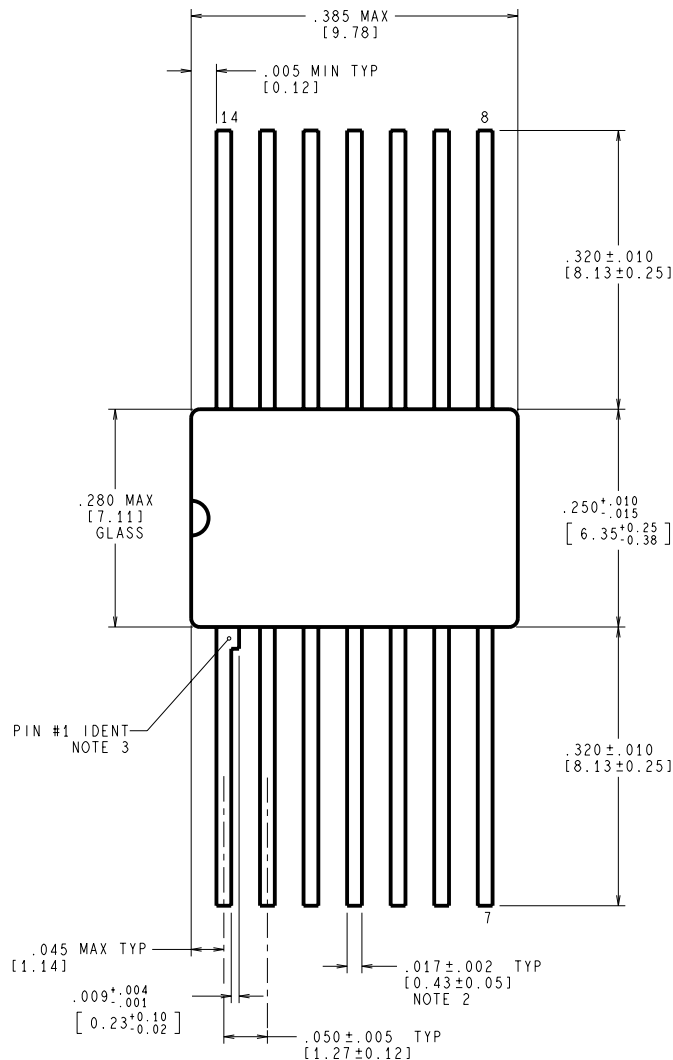


$.070^{+.010}_{-.020}$
[1.78 $^{+0.25}_{-0.50}$]

$.034^{+.011}_{-.008}$
[0.86 $^{+0.27}_{-0.20}$]

$.006 \pm .002$ TYP
[0.15 ± 0.05]
NOTE 2



REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
L	REVISE AND REDRAW PER NEW STANDARD.	10513	07/26/94	DEG/AEP
M	.017 ± .002 WAS .017 ± .020.	10655	10/21/94	DEG/CD
N	L/F THKS .006 ± .002 WAS .005 ± .001; UPDATE NOTES 1 & 2; REMOVE NOTE 4; UPDATE MILAERO STAMP; DUAL DIM'S WERE INCHES ONLY.	11005	06/08/95	MS/

NOTES: UNLESS OTHERWISE SPECIFIED.

1. LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO MIL-I-38535 TO A MINIMUM THICKNESS OF 200 MICROINCHES/ 5.08 MICROMETERS. SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE.
2. MAXIMUM LIMIT MAY BE INCREASED BY .003 INCHES/ 0.08 MILLIMETERS AFTER LEAD FINISH APPLIED.
3. LEAD 1 IDENTIFICATION SHALL BE:
 - a) A NOTCH OR OTHER MARK WITHIN THIS AREA
 - b) A TAB ON LEAD 1, EITHER SIDE

CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

MIL-I-38535
CONFIGURATION CONTROL

APPROVALS		DATE		 2900 Semiconductor dr., Santa Clara, CA 95052-8090	
DRAWN <i>D. E. Grady</i>		07/26/94			
DFTG. CHK.					
ENGR. CHK.					
 INCH [MM]				CERPACK, 14 LEAD	
SCALE N/A		SIZE C	DRAWING NUMBER MKT-W14B	REV N	
DO NOT SCALE DRAWING				SHEET 1 of 1	